

Reference 5: Japanese Patent Application Laid Open No. H6-75364

Title of the Invention: Mask for Exposure

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Applicant: Fujitsu Ltd.

Extract:

See Fig. 1. A pellicle film 16a is secured to pellicle frames 15a and 15b using adhesive (a) 17a and 17b, and a pellicle film 16b is secured to pellicle frames 15c and 15d using adhesive (a) 17c and 17d. An adhesive (b) 19a and an adhesive (c) 20a are bonded using a double-faced tape 18a between the pellicle frame 15a and a mask 11. The same holds true for between the mask 11 and the pellicle frames 15b, 15c and 15d.

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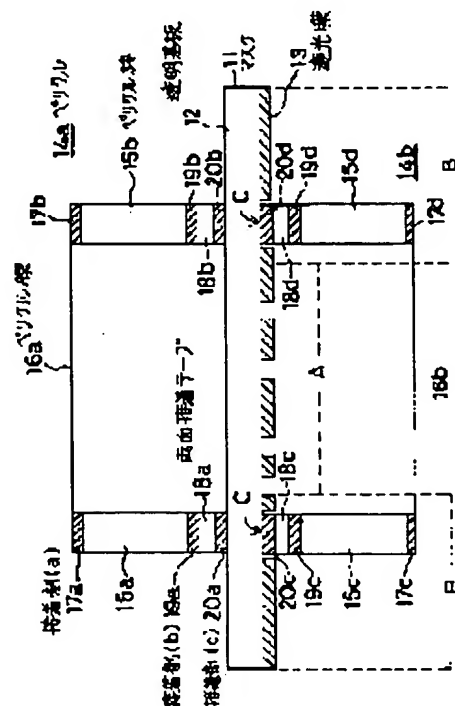
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(57)Abstract:

**PURPOSE:** To obtain a mask for exposure for a reticle or mask to be used at the time of transferring a circuit pattern on a wafer or glass substrate in the production of semiconductor device or liquid crystal display device, in which stain of the mask is prevented when the pellicle is peeled from the mask, the mask or pellicle is reused without damage, and further the positional accuracy of a pellicle to be stuck to the mask is improved.

**CONSTITUTION:** The mask consists of a transparent substrate 12 and light shielding film 13 formed on the one surface of this transparent substrate 12. The light shielding film 13 consists of a circuit pattern region 'A' where the circuit pattern to be transfer object is formed and a non-circuit pattern region 'B' where no circuit pattern is formed. In the non-circuit pattern region 'B', the part of the light shielding film 13 where the pellicle 14a, 14b is to be stuck is removed to make a pellicle frame 15a, 15b, 15c, 15d, which forms a region 'C' to stick the pellicle.



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